



OPLGA

Optical Land Grid Array Package

DESCRIPTION	SPECIFICATIONS
LINGSEN's Optical Land Grid Array (OPLGA) package is a clear-plastic- encapsulated package. OPLGA is suitable for the lighting and optical sensor device of the visible and IR application. The package molded on BT substrate is benefit to mass production. The leads of OPLGA are located around the bottom periphery of the package to provide short electrical connection to the PWB.	<ul style="list-style-type: none"> ✦ Substrate BT, thickness = 0.56 mm ✦ Gold Wire 99.99% Au ✦ Mold Compound NT-330HQ-10000 (Green) ✦ Transittance 90% @ wavelength 400nm ✦ Lead Au Plated Foot Print ✦ Marking White Ink ✦ Packing Tube

APPLICATIONS	RELIABILITY
<ul style="list-style-type: none"> Storage Products DVD Reader Lighting and Optical Sensor Products 	<ul style="list-style-type: none"> MSL Level JEDEC Level 3 @ + 255°C Temperature Cycling 500 cycles (-40°C /85°C) Temperature & Humidity Test 1,000 hrs (60°C/90%RH) High Temperature Storage 500 hrs (85°C) Low Temperature Storage 500 hrs (-40°C)

FEATURES
<ul style="list-style-type: none"> Clear Mold Compound Visible and IR Application BT Substrate Small and Thin scale Full In-house design capability

PACKAGE AVAILABILITY			
Package	Body Size (mm)	Die Size (mm)	Thermal Performance θ_{ja} (°C/W)
OPLGA 6L	2.35x1.8	1x0.8855x0.2032	132.18

Note: Simulated with JEDEC Standard 4-layer test board under still air condition, ambient temperature 45°C

ELECTRICAL PERFORMANCE					
Package	Body Size (mm)	Frequency (MHz)	Self Inductance (nH)	Self Capacitance (pF)	Resistance (mohm)
OPLGA 6L	2.35x1.8	100	1.170x1.277	0.185x0.478	52.154x63.900

Note: Results are simulated. Data is available through 1GHz.

CROSS-SECTION

